32. (New) The mounting socket of claim 31 where the conductive polymer is deformable when the spring is compressed.

33. (New) The mounting socket of claim 30 where the vias have a constant width.

34. (New) The mounting socket of claim 30 where the conductive polymer fills the vias from side to side.

35. (New) The mounting socket of claim 34 where the conductive polymer fills the vias from end to end.

36. (New) The mounting socket of claim 30 where the terminals extend beyond the first and second sides of the body.

37. (New) The mounting socket of claim 30 where the terminals are solderless.

38. (New) The mounting socket of claim 30 further comprising a first adhesive layer affixed to the first side of the body.

39. (New) The mounting socket of claim 38 further comprising:
a polymer tape applied to the first adhesive layer;
a ground and power line circuit on the polymer tape.

40. (New) The mounting socket of claim 39 further comprising a second adhesive layer applied over the ground and power line circuit.

41. (New) The mounting socket of claim 30 further comprising a further adhesive layer affixed to the second side of the body.

42. (New) A circuit assembly, comprising:

a substrate having a plurality of lands thereon;

a socket body having a first side in contact with the substrate, and having an opposite side;

a plurality of vias extending from the first side to the second side;

a plurality of conductive terminals within the vias and contacting the lands, each terminal including

a spring extending through one of the vias and adapted to exert a return force when compressed,

a conductive polymer in contact with the spring and with the one via.

43. (New) The circuit assembly of claim 42 where the conductive terminals exert a force upon the lands.

44. (New) The circuit assembly of claim 42 further comprising an adhesive layer bonding the socket body to the substrate.

45. (New) The circuit assembly of claim 42 further comprising an integrated circuit coupled to the substrate.

46. (New) The circuit assembly of claim 45 further comprising a circuit board contacting the opposite side of the socket body.

47. (New) The circuit assembly of claim 46 further comprising another adhesive layer on the opposite side of the socket body bonding it to the circuit board.

48. (New) A method, comprising:

fabricating a plurality of vias having constant widths through a socket body having first and second sides;

placing springs in the vias extending past ends of the vias so as to provide a return force when compressed to the ends of the vias;

injecting a conductive polymer into the vias so as to contact the springs and sides of the vias.

49. (New) The method of claim 48 where the springs are coil springs.

50. (New) The method of claim 48 further comprising applying an adhesive layer to the first side of the socket body.

51. (New) The method of claim 50 further comprising adhering a substrate to the first side of the socket body

52. (New) The method of claim 51 further comprising mounting an integrated circuit to the substrate.

53. (New) The method of claim 48 further comprising applying an adhesive layer to the second side of the socket body.

54. (New) A method, comprising:

providing a socket including

a body having first and second sides, and having a plurality of vias extending from a first side to a second side,

a plurality of conductive terminals within the vias, each terminal having a spring extending through one of the vias and adapted to exert a return force when compressed and a conductive polymer in contact with the spring and with the one via;